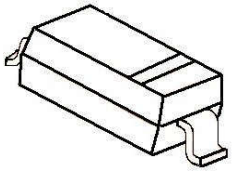
ASB0520-0540WEX0

SOD-123

SOD-123 贴片塑封肖特基二极管

SOD-123 Plastic-Encapsulate Schottky Barrier Diode



MARKING: ASB0520WEX0: SD
ASB0530WEX0: SE
ASB0540WEX0: SF

特征 Features

- 大电流承受能力。High Current Capability
- 正向压降低。Low Forward Voltage Drop

机械数据 Mechanical Data

- 封装: SOD-123 封装 SOD-123 Small Outline Plastic Package
- 极性: 色环端为负极 Polarity: Color band denotes cathode end
- 环氧树脂 UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25℃ 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25℃ ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	0520W	0530W	0540W	单位 Unit
最大可重复峰值反向电压 Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	V
最大均方根电压 Maximum RMS voltage	V_{RMS}	14	21	28	V
最大直流阻断电压 Maximum DC blocking voltage	V_{DC}	20	30	40	V
最大正向平均整流电流 Maximum average forward rectified current	I_{FM}	0.5			A
峰值正向浪涌电流 8.3ms 单一正弦半波 Peak forward surge current 8.3 ms single half sine-wave	I_{FSM}	5.5			A
典型热阻 Typical thermal resistance	$R_{\theta JA}$	200			℃/W
功率消耗 Power Dissipation	PD	500			mW
存储温度 Storage temperature range	T_{STG}	-50-+150			℃
Voltage rate of change	Dv/dt	1000			V/uS

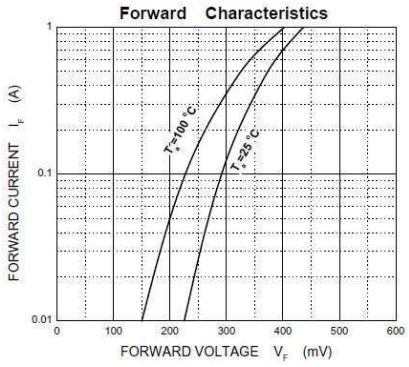
电特性 (TA = 25℃ 除非另有规定)

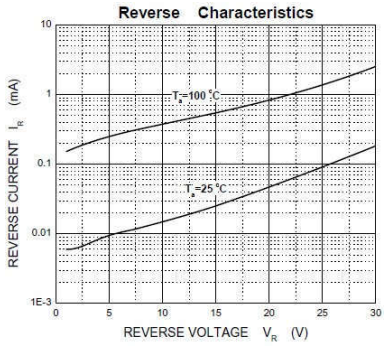
Electrical Characteristics (Ratings at 25℃ ambient temperature unless otherwise specified).

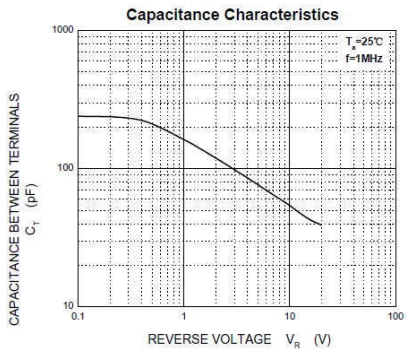
参数 Parameters	符号 Symbol	测试条件 Test conditions	B0520W	B0530W	B0540W	单位 Unit
最大正向电压 Maximum forward voltage	V_F	IF = 0.1A	0.330	0.375	---	V
		IF = 0.5A	0.385	0.430	0.510	
		IF = 1.0A	---	---	0.620	
最大反向电压 Maximum reverse breakdown voltage	VR	IR=250uA	20	---	---	V
		IR=200uA	---	30	---	
		IR=20.0uA	---	---	40	
最大反向电流 Maximum reverse current	I_R	VR=10V	75	---	---	uA
		VR=15V	---	20	---	
		VR=20V	250	---	10	
		VR=30V	---	130	---	
		VR=40V	---	---	20	
Capacitance between terminals	C_T	VR = 0V, f = 1MHz			170	pF

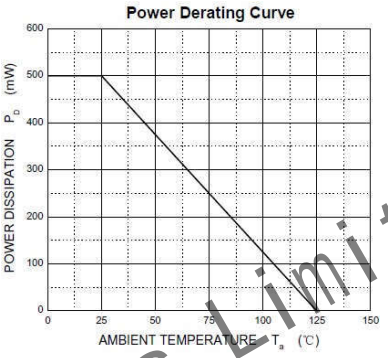
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特性曲线Characteristic Curves

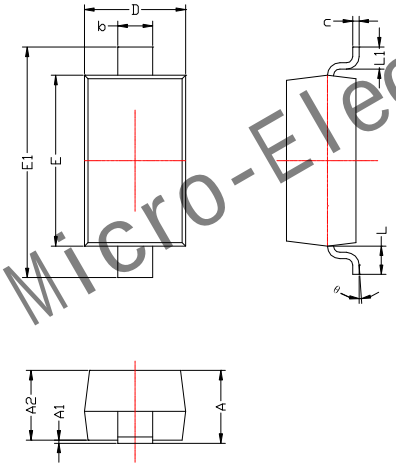








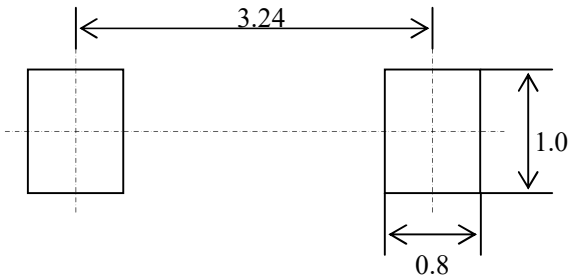
SOD-123 PACKAGE OUTLINE Plastic surface mounted package



SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.450	0.650
c	0.080	0.150
D	1.500	1.700
E	2.600	2.800
E1	3.550	3.850
L	0.500REF	
L1	0.250	0.450
θ	0°	8°

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焊盘设计参考Precautions: PCB Design(Recommended land dimensions for SOD-123 diode. Electrode patterns for PCBs)



中心距: 3.24
脚 宽: 0.55
焊盘宽: 1.00
脚 长: 0.50
焊盘长: 0.80

技术要求:
1, 塑封体尺寸: 2.70 X 1.60
2: 未注公差为: ±0.05
3, 所有单位: mm